

Electronic Patent Application Fee Transmittal

Application Number:	10811999			
Filing Date:	30-Mar-2004			
Title of Invention:	METHOD OF MANUFACTURING A SEMICONDUCTOR PACKAGE USING A LEAD FRAME HAVING THROUGH HOLES OR HOLLOWS THEREIN			
First Named Inventor/Applicant Name:	Kenichi Shirasaka			
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Attorney Docket Number:	X2007.0158			
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Utility Filing Fees				
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Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Printed copy of patent - no color	8001	10	3	30
Total in USD (\$)				1730